PLEASE AMEND THE SPECIFICATION AS INDICATED BELOW:

Please substitute the following Abstract for the Abstract as originally filed:

A method is provided for processing leadframe items of two or more types to form integrated circuit packages. The leadframe items are delivered along respective input paths and are received into holders, which are moved alternately between a processing region and a respective leadframe item reception position on a respective input path such that each of the holders moves to the processing region at a time when the other of the holders moves to its respective reception position. The leadframe items are delivered from the respective reception position to the processing region, and are then sent for encapsulation.

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